

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6902xxxxPR-G

Typical Mass: 53 mg

| Part name | Weight(mg) | Material name | Ratio(ppm) | CAS number |
|--------------|------------|-----------------|------------|------------|
| Silicon chip | 0.513 | Silicon | 9700 | 7440-21-3 |
| | | | | |
| Leadframe | 24.392 | Copper | 460200 | 7440-50-8 |
| | 0.016 | Tin | 300 | 7440-31-5 |
| | 0.218 | Silver | 4100 | 7440-22-4 |
| | | | | |
| Die attach | 0.126 | Silver | 2400 | 7440-22-4 |
| | 0.032 | Epoxy | 600 | — |
| | | | | |
| Bonding wire | 0.051 | Gold | 1000 | 7440-57-5 |
| | | | | |
| Resin | 23.565 | Silica | 444600 | 60676-86-0 |
| | 1.923 | Epoxy resin | 36300 | — |
| | 1.388 | Phenol resin | 26200 | — |
| | 0.376 | Metal hydroxide | 7100 | — |
| | | | | |
| Plating | 0.400 | Tin | 7500 | 7440-31-5 |
| | | | | |

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."